Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

These assemblies are ESD sensitive, ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Components marked 'DNP' should not be populated.

Assembly Variant: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: TIDA-00998</th>
<th>REV: E2</th>
<th>SUN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td>LAYER NAME = M5 Assembly Top</td>
<td>TID #: TIDA-00998</td>
<td></td>
<td></td>
</tr>
<tr>
<td>PLOT NAME = Top Assembly Drawing</td>
<td>GENERATED : 3/29/2017 10:41:16 AM</td>
<td></td>
<td>TEXAS INSTRUMENTS</td>
</tr>
</tbody>
</table>
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-00998</th>
<th>REV: E2</th>
<th>SVN REV: Not In VersionControl</th>
</tr>
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<tbody>
<tr>
<td>LAYER NAME = M6 Assembly Bottom</td>
<td>TID #: TIDA-00998</td>
<td></td>
<td></td>
</tr>
<tr>
<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 3/29/2017 10:41:17 AM</td>
<td></td>
<td>TEXAS INSTRUMENTS</td>
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</tbody>
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